

SCMOS-Like Design Rules for Sky130 on a 0.05- μ m Snapping Grid

Polysilicon (poly):

- min width 3
- min spacing 5

N Diffusion (ndiff):

- min width 3
- min spacing 6
- min spacing to poly 2
- min spacing to psd 6
- min spacing to nwell 7
- min extension of poly 3

P Substrate Diffusion (psd):

- min width 3
- min spacing 6
- min area 28
- min spacing to nwell 3

P Diffusion (pdiff):

- min width 3
- min spacing 6
- min spacing to poly 2
- min spacing to nsd 6
- min surround by nwell 4
- min extension of poly 3

N Substrate Diffusion (nsd):

- min width 3
- min spacing 6
- min area 28
- min surround by nwell 4

Poly Contact (pc):

- min size 4x4
- min surround by poly 2
- min surround by li 2

N Diffusion Contact (ndc):

- min size 4x4
- min surround by ndiff 3
- min surround by li 2

P Substrate Contact (psc):

- min size 4x4
- min surround by psd 3
- min surround by li 2

P Diffusion Contact (pdc):

min size 4x4
min surround by psd 3
min surround by li 2

N Substrate Contact (nsc):

min size 4x4
min surround by nsd 3
min surround by li 2

Local Interconnect (li):

min width 4
min spacing 4
min area 23

Metal Contact (mcon):

min size 4x4
min surround by li 2
min surround by m1 2

Metal1 (m1):

min width 3
min spacing 3
min area 34

Via (via):

min size 6x6
min surround by m1 1
min surround by m2 1

Metal2 (m2):

min width 3
min spacing 3
min area 28

Via2 (via2):

min size 6x6
min surround by m2 1
min surround by m3 1

Metal3 (m3):

min width 6
min spacing 6
min area 96

Via3 (via3):

min size 8x8
min surround by m3 1
min surround by m4 1

Metal4 (m4):

min width 6
min spacing 6
min area 96

Via4 (via4):

min size 24x24
min surround by m4 1
min surround by m5 3

Metal5 (m5):

min width 32
min spacing 32
min area 1600